

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent No.: 7,196,417 B2

Applicant(s): Tomohei SUGIYAMA et al.

Issued: March 27, 2007

Customer No.: 85775

For: METHOD OF MANUFACTURING A LOW EXPANSION MATERIAL AND
SEMICONDUCTOR DEVICE USING THE LOW EXPANSION MATERIAL

REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

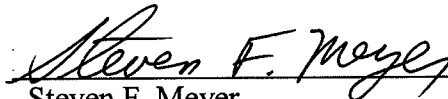
Sir:

Attached in duplicate is Form PTO-1050, with at least one copy being suitable for printing.

- ☐ The error was the fault of the Patent and Trademark Office, no fee is required.
- ☒ The error was not the fault of the Patent and Trademark Office, please charge the requisite fee of \$100 to Deposit Account No. 504827, Order No. 1004378.51180.
- ☒ The Commissioner is hereby authorized to charge any additional fees which may be required by this paper, or credit any overpayment to Deposit Account No. 504827, Order No. 1004378.51180.

Respectfully submitted,
Locke Lord Bissell & Liddell LLP

Dated: September 10, 2009


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UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NUMBER : 7,196,417 B2
DATED : March 27, 2007
INVENTOR(S) : Tomohei SUGIYAMA et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

IN THE SPECIFICATION

Column 1, line 28, please delete "in thermal" and insert therefore - - in the thermal - -;

Column 1, line 29, please delete "Si or other" and insert therefore - - Si or any other - -;

Column 1, line 30, please delete "5 and Al" and insert therefore - - 5, and Al - -;

Column 2, line 60, please delete "unsintered Sic particles" and insert therefore - - unsintered SiC particles - -;

Column 2, line 67, please delete "expan" and insert therefore - - expan- - -;

Column 4, line 5, please delete "as low thermal" and insert therefore - - as low a thermal -;

Column 4, line 55, please delete "The mold/melt temperature is set to" and insert therefore - - The mold/melt temperature is set to 700/800°C for each of Samples S5 to S8. - -;

Column 5, line 61, please delete "as heat spreader" and insert therefore - - as a heat spreader -; and

Column 6, line 7, please delete "as heat spreader" and insert therefore - - as a heat spreader -.

ADDRESS ASSOCIATED WITH CUSTOMER NUMBER: **85775**

PATENT NO. **7,196,417 B2**

No. of additional copies



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